

Mechanical behavior of materials - proceedings of the 1973 Symposium on Mechanical Behavior of Materials ; Kyoto, August 21-23, 1973

Society of Materials Science, Japan - Investigations on mechanical behavior of Al7075



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Effects of load and thermal histories on mechanical behavior of materials; Proceedings of the Symposium, Denver, CO, Feb. 25, 26, 1987 (Conference)

The mechanical behavior of these materials is generally modelled by considering the deformation of a unit cell Green and Lange, 1982, Gibson and Ashby, 1982, Ashby, 1983.

Mechanical behavior of materials

The organization or individual who handles the printing and distribution of printed or digital publications is known as Publisher. In this respect, the first volume of this work deals with elastic, elastoplastic, elastoviscoplastic and viscoelastic behaviours; this second volume continues with fracture mechanics and damage, and with contact mechanics, friction and wear. The ISSN of Journal of the Mechanical Behavior of Biomedical Materials journal is 17516161.

Journal of the Mechanical Behavior of Biomedical Materials

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MECHANICAL BEHAVIOR OF CELLULAR CERAMICS

It is used for the recognition of journals, newspapers, periodicals, and magazines in all kind of forms, be it print-media or electronic. Special attention is given to isothermal fatigue failure mechanisms in low-tin lead-based solder, the stress and strain controlled low-cycle fatigue of Pb-Sn solder for electronic packaging applications, load sequence effects on the deformation of isolated microplastic grains, and thermal fatigue of stainless steel. Chapter VII is devoted to hydrogen embrittlement and to environment assisted cracking, chapter VIII to creep damage.

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